

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S140	37	((thermal heat) near (dissipat\$3 sink spreader)) with (wir\$4 near line\$1)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB	OR	ON	2005/10/06 07:15
S141	7	module AND (packag\$3 substrate) AND terminal\$1 AND ((wir\$3 metal conduct\$3) NEAR line\$1) AND (power NEAR (switch\$3 device\$1 chip\$1 die\$1 transistor\$1)) AND electrode\$1 AND mount\$3 AND ((integrated NEAR circuit) IC) AND ((heat thermal) NEAR (sink dissipat\$3)) AND (electrically NEAR connect\$3) AND (resin seal\$3 encapsulat\$3).CLM.	US-PGPUB; USPAT	OR	ON	2005/10/06 07:26